



Microelectronic Packaging & Assembly Solutions

Quik-Pak Exhibits Prototype Services for RF Devices and Sensors Supporting 5G and IoT in Booth 408 at ECTC in San Diego, May 29 - June 1, 2018

San Diego, CA – May 29, 2018 – Quik-Pak, a division of Promex and provider of IC packaging, assembly, and wafer preparation services, is exhibiting prototype services for RF devices and sensors supporting 5G and IoT in Booth 408 at the Electronic Components and Technology Conference. Held at the Sheraton San Diego Hotel & Marina in San Diego, Calif. May 29 through June 1, 2018, ECTC brings together the best in packaging, components and microelectronic systems science, technology and education in an environment of cooperation and technical exchange. This international event, sponsored by the IEEE Electronics Packaging Society (formerly CPMT), includes a technical program covering leading-edge developments and technical innovations across the packaging spectrum.

Earlier this year, Quik-Pak announced that it can deliver assembled QFNs in five days, with quick-turn engineering builds for custom overmolded QFN packages available in as little as five weeks after validation of the customer's design. The QFNs are available in over 35 designs, with multiple thicknesses. Package sizes range from 2x2 mm to 12x12 mm for QFNs, as well as 1.5x1.5 mm to 4x4 mm for DFNs. All are RoHS compliant and utilize NiPdAu-plated lead frames.

Quik-Pak provides high-volume IC assembly services utilizing automated assembly and molding equipment for production runs in the 10,000s of units from its ISO 9001:2008-certified and ITAR-registered facility in San Diego, California. In addition to wire bond assembly, the company assembles flip chips, BGAs, stacked die, sensors, MEMS, chip-on-board (COB) and chip-on-flex assemblies. More information is available at <http://www.icproto.com> or by calling 858-674-4676.